

## **Final Product Change Notification**

Issue Date: 29-Jan-2016 Effective Date: 12-May-2016

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# 201601006F01



### **Management Summary**

The TEF663xHW/V106Z dual sourcing version is available (Waferfab: Globalfoundries and TSMC: Assembly: ATKH - NXP Taiwan).

#### Change Category

[]Wafer Fab materials [X] Wafer Fab location

[X] Assembly Materials [] Assembly Location [] Test Location

[] Wafer Fab process [] Assembly Process [X] Product Marking [] Electrical spec./Test coverage

[] Design [] Mechanical Specification

[] Packing/Shipping/Labeling

# TEF663xHW/V106Z - Hero dual sourcing

### **Details of this Change**

As part of the NXP Business Continuity Management (BCM) program it has been decided to establish a dual sourcing for the HERO product family. NXP strongly recommends customers to switch over to TEF663xHW/V106Z.

The GF version TEF663xHW/V106 (Cu wire) is for more than 1 year in production and the TSMC version TEF663xHW/V105 for more than 4 years.

The following changes have been applied to the TSMC version:

ROM code version V106 (compatible to V105 in features, functions and performance)

Introduction of Cu wire

The actual sourcing is finally at NXP's discretion.

The TEF663xHW/V105 versions are planned to be discontinued in June 2016.

For the TEF663xHW/V106 version, NXP recommends to change over to the V106Z version to benefit from improved supply security and business continuity, although this change-over is not mandatory.

### Why do we Implement this Change

1. Support continuous customer deliveries in case of major natural disasters / significant business interruptions

2. To meet customers demand and support future growth by increasing flexibility and capacity

3. Align with world-class technology trends

### Identification of Affected Products

Top side marking

- 1. 3rd line depending on the waferfab source
- 2. "kSD" : Waferfab TSMC, Taiwan
- 3. "sSD": Waferfab GF, Singapore

**Product Availability** 

Sample Information Samples are available upon request Production Planned first shipment 29-Apr-2016

#### Impact

no impact to the product's functionality anticipated. **Data Sheet Revision** No impact to existing datasheet **Disposition of Old Products** Existing inventory will be shipped until depleted

**Timing and Logistics** 

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 28-Feb-2016. Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

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## NXP Quality Management Team.

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Changed Orderable Part#	New Orderable Part#
TEF6638HW/V105,557	TEF6638HW/V106ZK